

ABSTRACT

METHOD FOR MOUNTING A FLIP CHIP ON A SUBSTRATE

The invention concerns a method for mounting a semiconductor chip (2) with bumps (1) on one surface onto a substrate location (3) of a substrate (4), whereby the bumps (1) are brought into contact with corresponding pads (10) on the substrate location (3). Reference marks (12, 13) are attached to the
5 bondhead (6) that enable measurement of the actual position of the semiconductor chip (2) as well as measurement of the actual position of the substrate location (3) in relation to a system of coordinates defined by the reference marks (12, 13). Positional displacement of the individual components of the assembly machine caused by thermal influences can be compensated without perpetual calibration procedures having to be carried out.

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(Fig. 1)